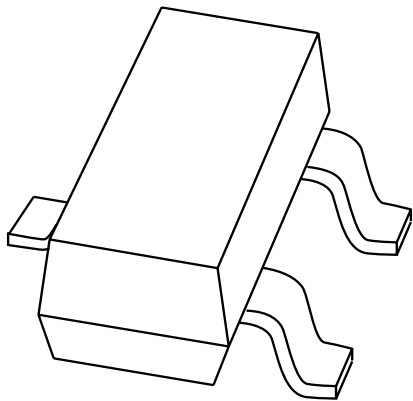


# DATA SHEET



**PBSS5230T**

30 V, 2 A

PNP low  $V_{CEsat}$  (BISS) transistor

Product specification

2003 Dec 18

# 30 V, 2 A PNP low $V_{CEsat}$ (BISS) transistor

**PBSS5230T**

## FEATURES

- Low collector-emitter saturation voltage  $V_{CEsat}$
- High collector current capability:  $I_C$  and  $I_{CM}$
- Higher efficiency leading to less heat generation
- Reduced printed-circuit board requirements
- Cost effective alternative to MOSFETs in specific applications.

## APPLICATIONS

- Power management
  - DC/DC converters
  - Supply line switching
  - Battery charger
  - LCD backlighting.
- Peripheral drivers
  - Driver in low supply voltage applications (e.g. lamps and LEDs)
  - Inductive load driver (e.g. relays, buzzers and motors).

## DESCRIPTION

PNP BISS transistor in a SOT23 plastic package offering ultra low  $V_{CEsat}$  and  $R_{CEsat}$  parameters.

## MARKING

TYPE NUMBER	MARKING CODE <sup>(1)</sup>
PBSS5230T	3K*

### Note

- \* = p: Made in Hong Kong.  
 \* = t: Made in Malaysia.  
 \* = W: Made in China.

## ORDERING INFORMATION

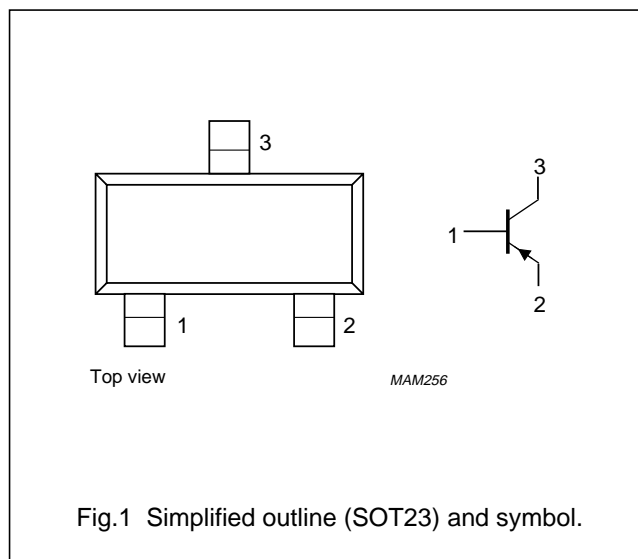
TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PBSS5230T	–	plastic surface mounted package; 3 leads	SOT23

## QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
$V_{CEO}$	collector-emitter voltage	–30	V
$I_C$	collector current (DC)	–2	A
$I_{CM}$	peak collector current	–3	A
$R_{CEsat}$	equivalent on-resistance	220	m $\Omega$

## PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



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**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CBO}$	collector-base voltage	open emitter	–	–30	V
$V_{CEO}$	collector-emitter voltage	open base	–	–30	V
$V_{EBO}$	emitter-base voltage	open collector	–	–5	V
$I_C$	collector current (DC)		–	–2	A
$I_{CM}$	peak collector current	single peak	–	–3	A
$I_B$	base current (DC)		–	–300	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$ ; note 1	–	300	mW
		$T_{amb} \leq 25\text{ °C}$ ; note 2	–	480	mW
$T_j$	junction temperature		–	150	°C
$T_{amb}$	operating ambient temperature		–65	+150	°C
$T_{stg}$	storage temperature		–65	+150	°C

**Notes**

1. Device mounted on a FR4 printed-circuit board; single-sided copper; tinplated; standard footprint.
2. Device mounted on a FR4 printed-circuit board; single-sided copper; tinplated; mounting pad for collector 1 cm<sup>2</sup>.

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	in free air; note 1	417	K/W
		in free air; note 2	260	K/W

**Notes**

1. Device mounted on a FR4 printed-circuit board; single-sided copper; tinplated; standard footprint.
2. Device mounted on a FR4 printed-circuit board; single-sided copper; tinplated; mounting pad for collector 1 cm<sup>2</sup>.

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**CHARACTERISTICS** $T_j = 25\text{ °C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{CBO}$	collector cut-off current	$V_{CB} = -30\text{ V}; I_E = 0$	–	–	–100	nA
		$V_{CB} = -30\text{ V}; I_E = 0; T_j = 150\text{ °C}$	–	–	–50	$\mu\text{A}$
$I_{EBO}$	emitter cut-off current	$V_{EB} = -4\text{ V}; I_C = 0$	–	–	–100	nA
$h_{FE}$	DC current gain	$V_{CE} = -2\text{ V}; I_C = -100\text{ mA}$	300	450	–	
		$V_{CE} = -2\text{ V}; I_C = -1\text{ A}; \text{note 1}$	200	290	–	
		$V_{CE} = -2\text{ V}; I_C = -2\text{ A}; \text{note 1}$	100	180	–	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -500\text{ mA}; I_B = -50\text{ mA}$	–	–70	–110	mV
		$I_C = -1\text{ A}; I_B = -50\text{ mA}$	–	–140	–225	mV
		$I_C = -2\text{ A}; I_B = -200\text{ mA}$	–	–240	–350	mV
$R_{CEsat}$	equivalent on-resistance	$I_C = -500\text{ mA}; I_B = -50\text{ mA}; \text{note 1}$	–	160	220	$\text{m}\Omega$
$V_{BEsat}$	base-emitter saturation voltage	$I_C = -2\text{ A}; I_B = -50\text{ mA}; \text{note 1}$	–	–	–1.1	V
$V_{BEon}$	base-emitter turn-on voltage	$V_{CE} = -2\text{ V}; I_C = -100\text{ mA}$	–	–	–0.75	V
$f_T$	transition frequency	$V_{CE} = -10\text{ V}; I_C = -100\text{ mA};$ $f = 100\text{ MHz}$	100	200	–	MHz
$C_C$	collector capacitance	$V_{CB} = -10\text{ V}; I_E = I_e = 0; f = 1\text{ MHz}$	–	23	28	pF

**Note**

1. Pulse test:  $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$ .

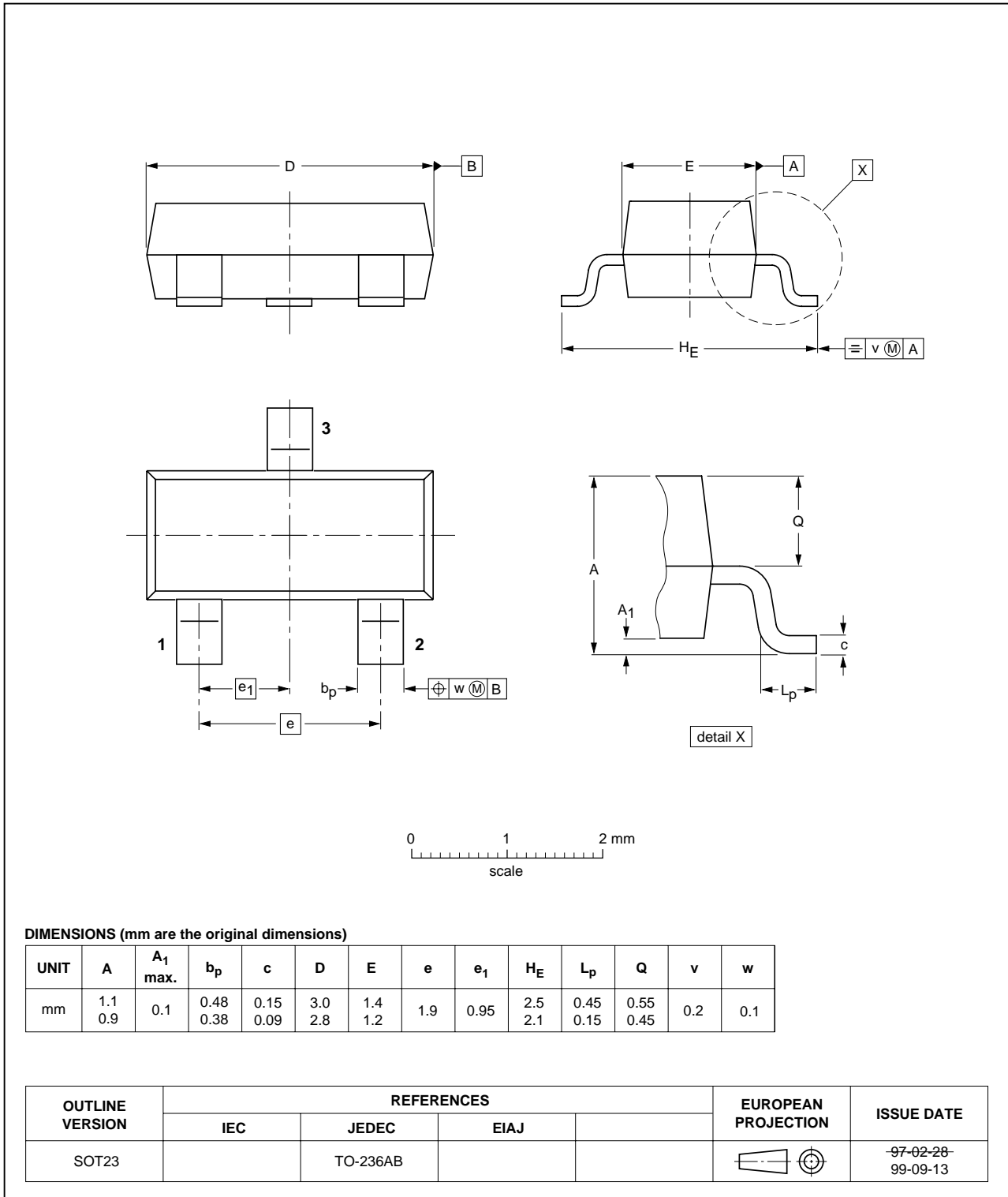
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PBSS5230T

PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT23



30 V, 2 A  
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PBSS5230T

## DATA SHEET STATUS

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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